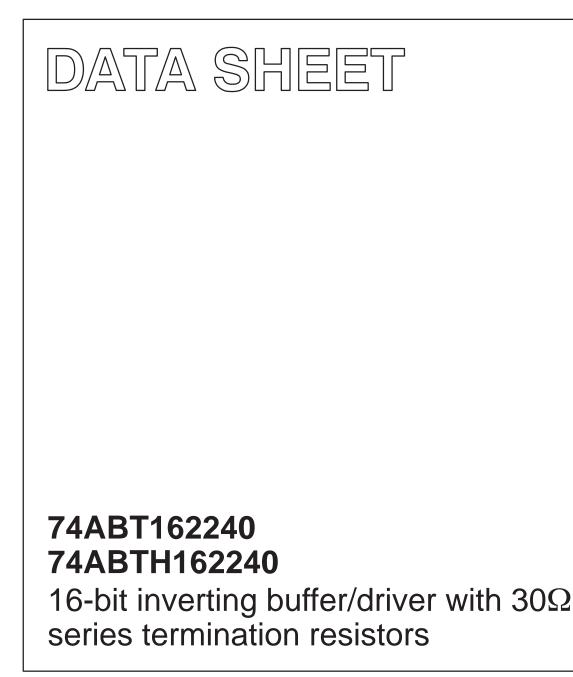
INTEGRATED CIRCUITS



Product specification Supersedes data of 1998 Jan 16 IC23 Data Handbook

1998 Feb 25



Philips Semiconductors

74ABT162240 74ABTH162240

FEATURES

- 16-bit bus interface
- 3-State buffers
- Output capability: +12mA/-32mA
- TTL input and output switching levels
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power-up 3-State
- 74ABTH162240 incorporates bus hold data inputs which eliminate the need for external pull up resistors to hold unused inputs
- Latch-up protection exceeds 500mA per JEDEC Std 17
- ESD protection exceeds 2000V per MIL STD 883 Method 3015 and 200V per Machine Model

QUICK REFERENCE DATA

DESCRIPTION

The 74ABT162240 is a high-performance BiCMOS device which combines low static and dynamic power dissipation with high speed.

This device is an inverting 16-bit buffer that is ideal for driving bus lines. The device features four Output Enables $(1\overline{OE}, 2\overline{OE}, 3\overline{OE}, 4\overline{OE})$, each controlling four of the 3-State outputs.

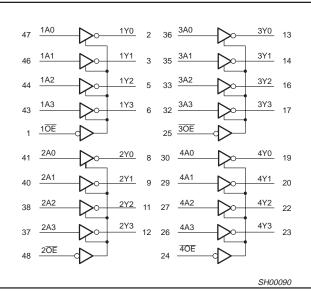
Two options are available, 74ABT162240 which does not have the bus hold feature and 74ABTH162240 which incorporates the bus hold feature.

SYMBOL	PARAMETER	CONDITIONS T _{amb} = 25°C	TYPICAL	UNIT
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	C _L = 50pF; V _{CC} =	2.7 2.6	ns
C _{IN}	Input capacitance nOE	$V_{I} = 0V \text{ or } 3.0V$	4	pF
C _{OUT}	Output capacitance	Outputs disabled; $V_0 = 0V$ or	6	pF
I _{CCZ}	Quiescent supply current	Outputs disabled; V _{CC} =	500	μΑ
I _{CCL}	Quescent supply current	Outputs low; $V_{CC} = 5.5V$	8	mA

ORDERING INFORMATION

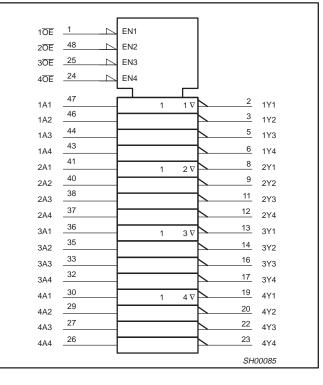
PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
48-Pin Plastic SSOP Type III	-40°C to +85°C	74ABT162240 DL	BT162240 DL	SOT370-1
48-Pin Plastic TSSOP Type II	-40°C to +85°C	74ABT162240 DGG	BT162240 DGG	SOT362-1
48-Pin Plastic SSOP Type III	-40°C to +85°C	74ABTH162240 DL	BH162240 DL	SOT370-1
48-Pin Plastic TSSOP Type II	–40°C to +85°C	74ABTH162240 DGG	BH162240 DGG	SOT362-1

LOGIC SYMBOL



74ABT162240 74ABTH162240

LOGIC SYMBOL (IEEE/IEC)



PIN CONFIGURATION

1 0E		48 2 0E
1Y0	2	47 1A0
1Y1	3	46 1A1
GND	4	45 GND
1Y2	5	44 1A2
1Y3	6	43 1A3
V _{CC}	7	42 V _{CC}
2Y0	8	41 2A0
2Y1	9	40 2A1
GND	10	39 GND
2Y2	11	38 2A2
2Y3	12	37 2A3
3Y0	13	36 3A0
3Y1	14	35 3A1
GND	15	34 GND
3Y2	16	33 3A2
3Y4	17	32 3A3
VCC	18	31 V _{CC}
4Y0	19	30 4A0
4Y1	20	29 4A1
GND	21	28 GND
4Y2	22	27 4A2
4Y3	23	26 4A3
40E	24	25 3 0 E
		SA00013

FUNCTION TABLE

Inp	uts	Outputs
nOE	nAx	nYx
L	L	Н
L	Н	L
Н	Х	Z

H = High voltage level

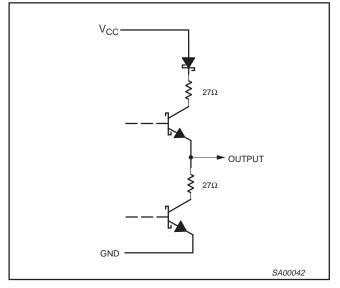
L = Low voltage level

X = Don't care

Z = High Impedance "off" state

74ABT162240 74ABTH162240

SCHEMATIC OF Y OUTPUTS



PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
47, 46, 44, 43, 41, 40, 38, 37, 36, 35, 33, 32, 30, 29, 27, 26	1A0-1A3 2A0-2A3 3A0-3A3 4A0-4A3	Data inputs
2, 3, 5, 6, 8, 9, 11, 12, 13, 14, 16, 17, 19, 20, 22, 23	170-173 270-273 370-373 470-473	Data outputs
1, 48, 25, 24	1 <u>0E,</u> 2 <u>0E,</u> 30E, 4 <u>0E</u>	Output enables
4, 10, 15, 21, 28, 34, 39, 45	GND	Ground (0V)
7, 18, 31, 42	V _{CC}	Positive supply voltage

74ABT162240 74ABTH162240

ABSOLUTE MAXIMUM RATINGS^{1, 2}

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +7.0	V
I _{IK}	DC input diode current	V ₁ < 0	-18	mA
VI	DC input voltage ³		-1.2 to +7.0	V
I _{OK}	DC output diode current	V _O < 0	-50	mA
V _{OUT}	DC output voltage ³	Output in Off or High state	-0.5 to +5.5	V
laum.	DC output current Output in Le	Output in Low state	128	mA
OUT		Output in High state	-64	
T _{stg}	Storage temperature range		-65 to +150	°C

NOTES:

 Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

 The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

3. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	UNIT	
STWBUL	PARAMETER	MIN	MAX	UNIT
V _{CC}	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V _{CC}	V
V _{IH}	High-level input voltage	2.0		V
V _{IL}	Input voltage		0.8	V
I _{OH}	High-level output current		-32	mA
I _{OL}	Low-level output current		32	mA
	Low-level output current; current duty cycle \leq 50%; f \geq 1kHz		12	
$\Delta t/\Delta v$	Input transition rise or fall rate; Outputs enabled	0	10	ns/V
T _{amb}	Operating free-air temperature range	-40	+85	°C

74ABT162240 74ABTH162240

DC ELECTRICAL CHARACTERISTICS

						LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS		Та	T _{amb} = +25°C			: –40°C 85°C	UNIT
				Min	Тур	Max	Min	Max	
V _{IK}	Input clamp voltage	V _{CC} = 4.5V; I _{IK} = -18mA			-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5V; I_{OH} = -3mA; V_{I} = V$	′ _{IL} or V _{IH}	2.5	2.9		2.5		V
V _{OH}	High-level output voltage	$V_{CC} = 5.0V; I_{OH} = -3mA; V_{I} = V$	′ _{IL} or V _{IH}	3.0	3.4		3.0		V
		$V_{CC} = 4.5V; I_{OH} = -32mA; V_{I} =$	V _{IL} or V _{IH}	2.0	2.4		2.0		V
V _{OL}	Low-level output voltage	$V_{CC} = 4.5$ V; $I_{OL} = 8$ mA; $V_{I} = V_{IL}$	or V _{IH}			0.65		0.65	V
VOL	Low-level output voltage	V _{CC} = 4.5V; I _{OL} = 12mA; V _I = V	_{IL} or V _{IH}			0.80		0.80	V
lj	Input leakage current	$V_{CC} = 5.5$ V; $V_{I} = $ GND or 5.5V			±0.01	±1.0		±1.0	μA
	Input leakage current	$V_{CC} = 5.5V; V_I = V_{CC} \text{ or GND}$	Control pins		±0.01	±1		±1	μA
I _I	74ABTH162240	$V_{CC} = 5.5 V; V_{I} = V_{CC}$	Data pins		0.01	1		1	μA
		$V_{CC} = 5.5 V; V_{I} = 0$	Data pins		-2	-3		-5	μA
		$V_{CC} = 4.5V; V_I = 0.8V$		50			50		
I _{HOLD}	Bus Hold current A inputs ³ 74ABTH162240	$V_{CC} = 4.5 V; V_I = 2.0 V$		-75			-75		μA
		$V_{CC} = 5.5$ V; $V_{I} = 0$ to 5.5V	$V_{CC} = 5.5V; V_{I} = 0 \text{ to } 5.5V$						
I _{OFF}	Power-off leakage current	V_{CC} = 0.0V; V_{O} or $V_{I} \le 4.5V$			±5.0	±100		±100	μA
I _{PU} /I _{PD}	Power-up/down 3-State output current	$V_{CC} = 2.0V; V_O = 0.5V; V_I = GND \text{ or } V_{CC};$ $V_{OE} = V_{CC}$			±5.0	±50		±50	μΑ
I _{OZH}	3-State output High current	$V_{CC} = 5.5$ V; $V_{O} = 2.7$ V; $V_{I} = V_{IL}$	or V _{IH}		1.0	10		10	μA
I _{OZL}	3-State output Low current	$V_{CC} = 5.5$ V; $V_{O} = 0.5$ V; $V_{I} = V_{IL}$	or V _{IH}		-1.0	-10		-10	μA
I _{CEX}	Output high leakage current	V _{CC} = 5.5V; V _O = 5.5V; V _I = GN	ID or V _{CC}		1.0	50		50	μA
Ι _Ο	Output current ¹	V _{CC} = 5.5V; V _O = 2.5V		-50	-70	-180	-50	-180	mA
I _{CCH}		V_{CC} = 5.5V; Outputs High, V _I =	GND or V _{CC}		0.5	1.0		1.0	mA
I _{CCL}	Quiescent supply current	V_{CC} = 5.5V; Outputs Low, V_{I} = 0	GND or V _{CC}		8	19		19	mA
I _{CCZ}		V_{CC} = 5.5V; Outputs 3-State; V ₁ = GND or V _{CC}			0.5	1.0		1.0	mA
ΔI_{CC}	Additional supply current per input pin ² 74ABT162240	Outputs enabled, one input at 3.4V, other inputs at V_{CC} or GND; $V_{CC} = 5.5V$			10	200		200	μA
ΔI_{CC}	Additional supply current per input pin ² 74ABTH162240	Outputs enabled, one input at 3 inputs at V_{CC} or GND; $V_{CC} = 5$.			0.2	1.0		1.0	mA

NOTES:

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
This is the increase in supply current for each input at 3.4V.

3. This is the bus hold overdrive current required to force the input to the opposite logic state.

74ABT162240 74ABTH162240

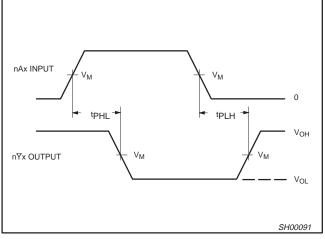
AC CHARACTERISTICS

GND = 0V; $t_R = t_F = 2.5ns$; $C_L = 50pF$; $R_L = 500\Omega$; $T_{amb} = -40^{\circ}C$ to $+85^{\circ}C$.

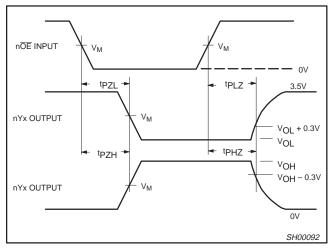
					LIMI	ſS		
SYMBOL	PARAMETER	WAVEFORM	T _é V	amb = +25° ′CC = +5.0′	C V	$T_{amb} = -40^{\circ}$ $V_{CC} = +5.$	°C to +85°C .0V ±0.5V	UNIT
			Min	Тур	Мах	Min	Max	
t _{PLH} t _{PHL}	Propagation delay nAx to nYx	1	1.0 1.0	2.7 2.6	3.8 3.2	1.0 1.0	4.2 3.7	ns
t _{PZH} t _{PZL}	Output enable time to High and Low level	2	1.2 1.0	2.3 2.9	3.2 3.8	1.2 1.0	4.0 4.7	ns
t _{PHZ} t _{PLZ}	Output disable time from High and Low level	2	1.6 1.4	3.0 2.8	4.1 3.8	1.6 1.4	4.7 4.0	ns

AC WAVEFORMS

 V_{M} = 1.5V, V_{IN} = GND to 2.7V



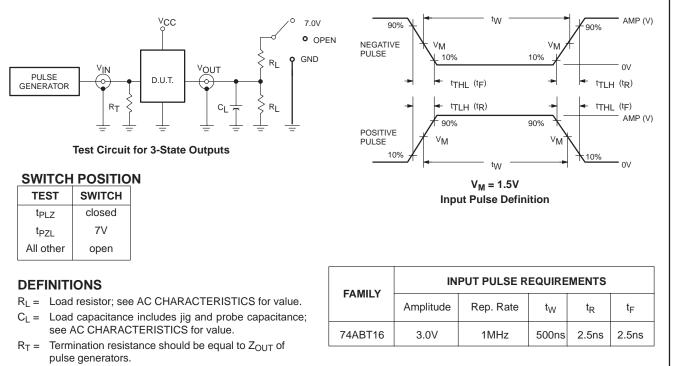
Waveform 1. Input (nAx) to Output (nYx) Propagation Delays



Waveform 2. 3-State Output Enable and Disable Times

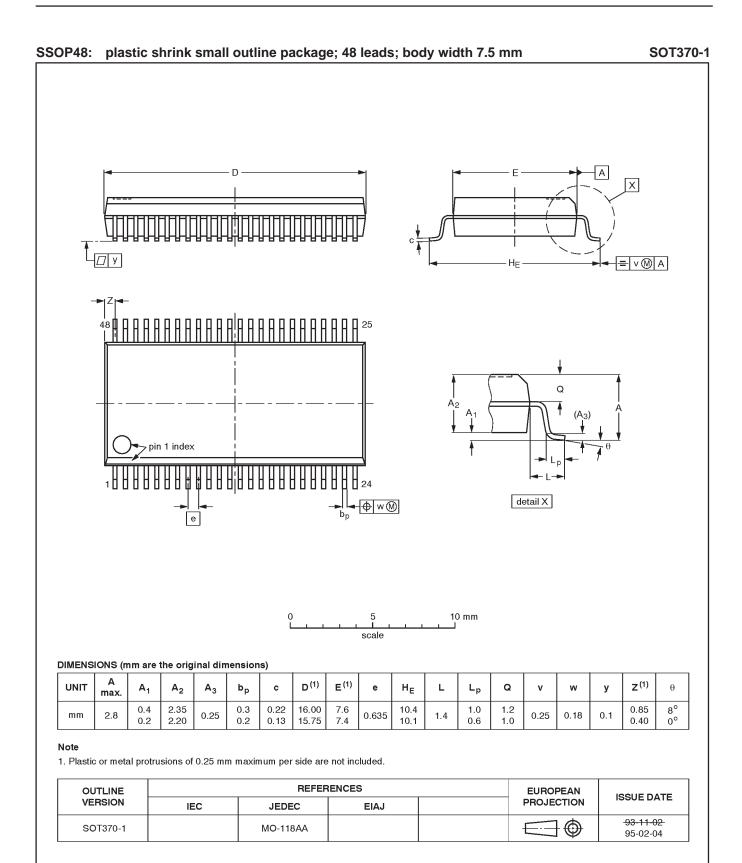
74ABT162240 74ABTH162240

TEST CIRCUIT AND WAVEFORMS

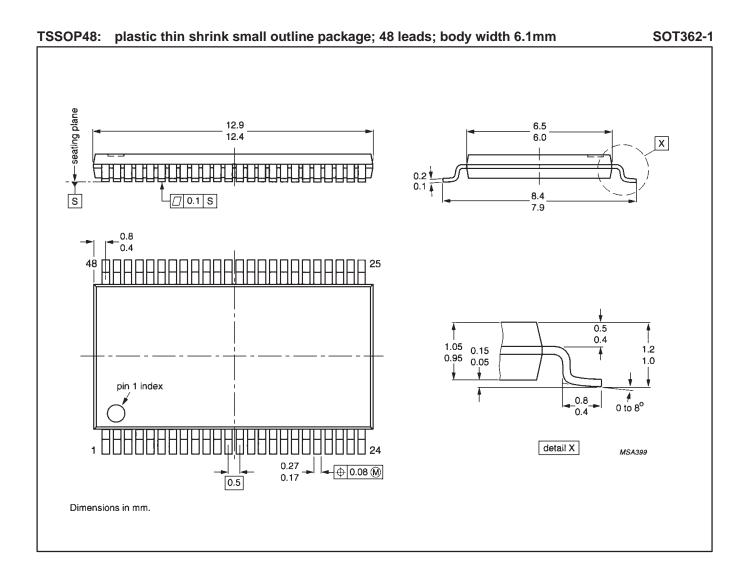


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74ABT162240 74ABTH162240



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NOTES

74ABT162240 74ABTH162240

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued datasheet before initiating or completing a design.

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